

## 600V N-Channel Super-Junction MOSFET Gen-II

### Description

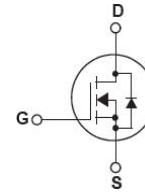
SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.

### Features

- Multi-Epi process SJ-FET
- Fast-Recovery body diode
- Extremely Low Reverse Recovery Charge
- 650V @TJ = 150 °C
- Typ. RDS(on) = 62mΩ
- Ultra Low Gate Charge (typ. Qg = 78nC)
- 100% avalanche tested



### Package Marking and Ordering Information:

Marking	Package	Part #	Hazardous Substance Control	Packing
SR60R075G	TO-247-3L	SR60R075G	Pb free	Tube
SR60R075T	TO-220-3L	SR60R075T	Pb free	Tube
SR60R075S	TO-263-2L	SR60R075S	Pb free	Reel

## Absolute Maximum Ratings

Symbol	Parameter	SR60R075T/S/G	Unit
V <sub>DSS</sub>	Drain-Source Voltage	600	V
I <sub>D</sub>	Drain Current-Continuous (TC = 25°C) -Continuous (TC = 100°C)	41* 26*	A
I <sub>DM</sub>	Drain Current - Pulsed (Note 1)	123	A
V <sub>GSS</sub>	Gate-Source voltage	±30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)	960	mJ
I <sub>AS</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>J</sub> max)	8	A
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15	V/ns
dV <sub>ds</sub> /dt	Drain Source voltage slope (V <sub>ds</sub> =480V)	50	V/ns
P <sub>D</sub>	Power Dissipation (TC = 25°C)	236	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150	°C
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/16" from Case for 10 Seconds	260	°C

\*Drain current limited by maximum junction temperature. Maximum duty cycle D=0.75

## Thermal Characteristics

Symbol	Parameter	SR60R075T/S/G	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	0.53	°C/W
R <sub>θCS</sub>	Thermal Resistance, Case-to-Sink Typ.	0.5	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62	°C/W

**Electrical Characteristics TC = 25°C** unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA, T <sub>J</sub> = 25°C	600	-	-	V
		V <sub>GS</sub> = 0V, I <sub>D</sub> = 1.5mA, T <sub>J</sub> = 150°C	650	-	-	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 1.5mA, Referenced to 25°C	-	0.6	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 600V, V <sub>GS</sub> = 0V -T <sub>J</sub> = 125°C	-	1 200	5 -	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	-	-	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 2.5mA	3.0	4.0	5.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	62	75	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V, f = 1.0MHz	-	3200	-	pF
C <sub>oss</sub>	Output Capacitance		-	140	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	3.7	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 400V, I <sub>D</sub> = 20A, V <sub>GS</sub> = 10V (Note 4)	-	78	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	23.4	-	nC
Q <sub>gd</sub>	Gate-Drain Charge		-	33.4	-	nC
V <sub>plateau</sub>	Gate plateau voltage		-	6.6	-	V
R <sub>g</sub>	Gate resistance	f=1 MHz, open drain	-	1	-	Ω
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> = 400V, I <sub>D</sub> = 20A R <sub>G</sub> = 3Ω, V <sub>GS</sub> = 10V (Note 4)	-	23	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	20	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	88	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	10	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		-	-	41	A

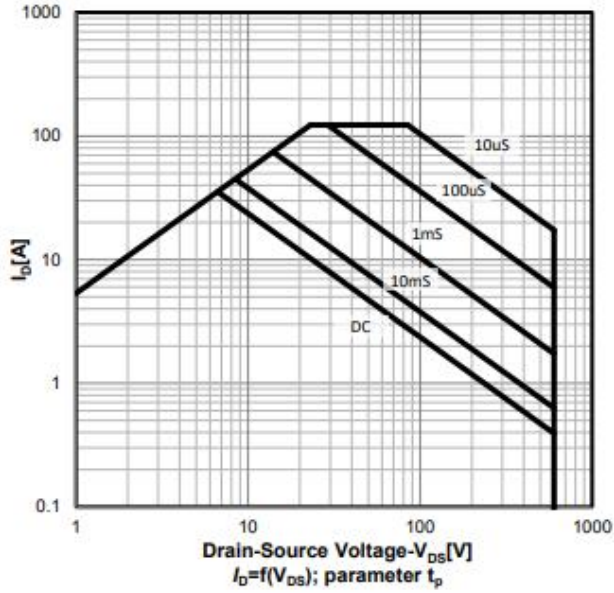
ISM	Maximum Pulsed Drain-Source Diode Forward Current		-	-	123	A
VSD	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_s = 20A$	-	0.9	1.4	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, V_{DS} = 400V,$ $I_s = 20A, di/dt = 100A/\mu s$	-	180	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	1.4	-	$\mu C$
$I_{rrm}$	Peak Reverse Recovery Current		-	16	-	A

**NOTES:**

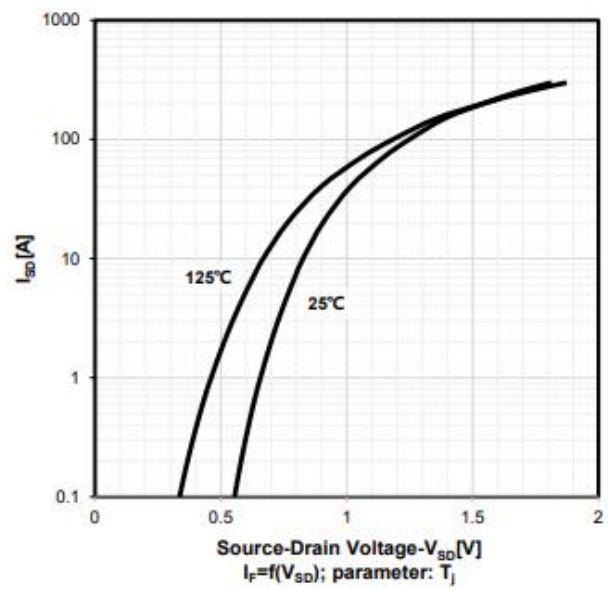
- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_D = I_{AS}, V_{DD} = 100V, L = 30mH,$  Starting  $T_J = 25\text{ }^\circ C$
3. $I_{SD} \leq I_D, di/dt \leq 200A/\mu s, V_{DD} \leq B_{VDSS},$  Starting  $T_J = 25\text{ }^\circ C$
- 4.Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

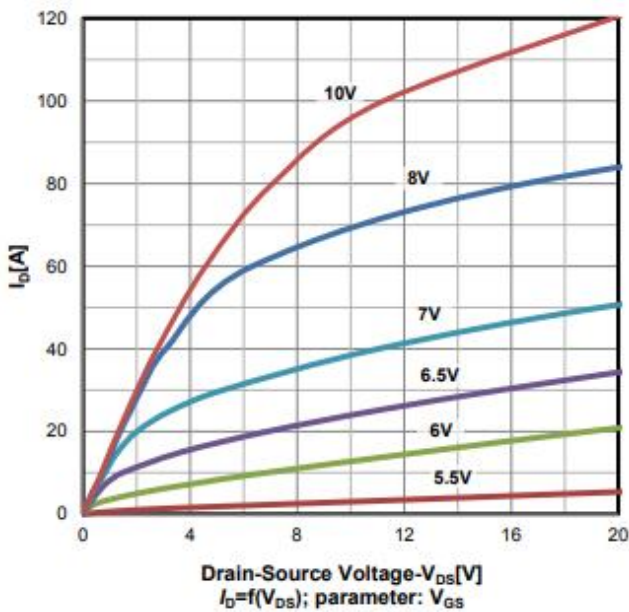
Typ. Safe operating area TC=25 °C



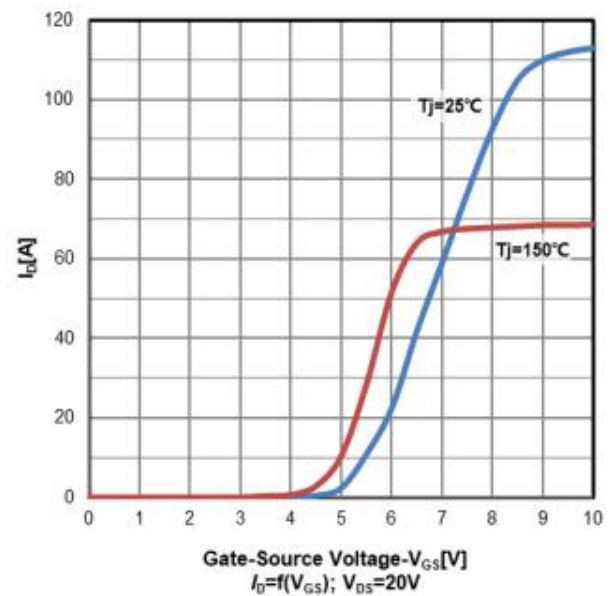
Typ. Forward characteristics of reverse diode



Typ. output characteristics  $T_J=25^\circ\text{C}$

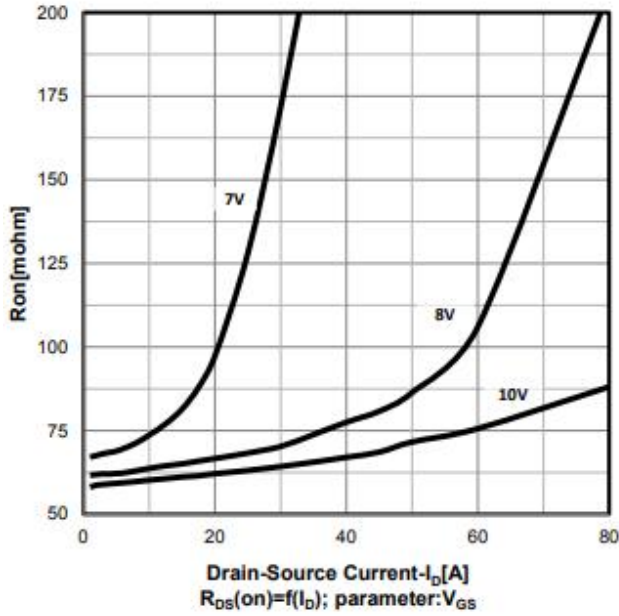


Typ. Transfer characteristics

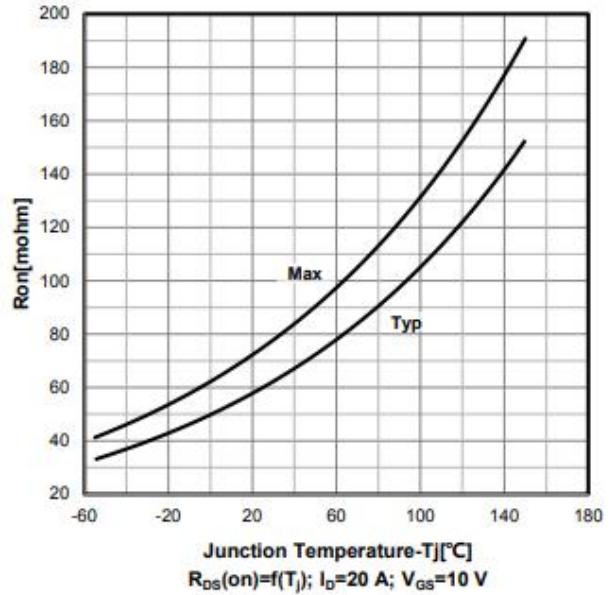


## Typical Performance Characteristics

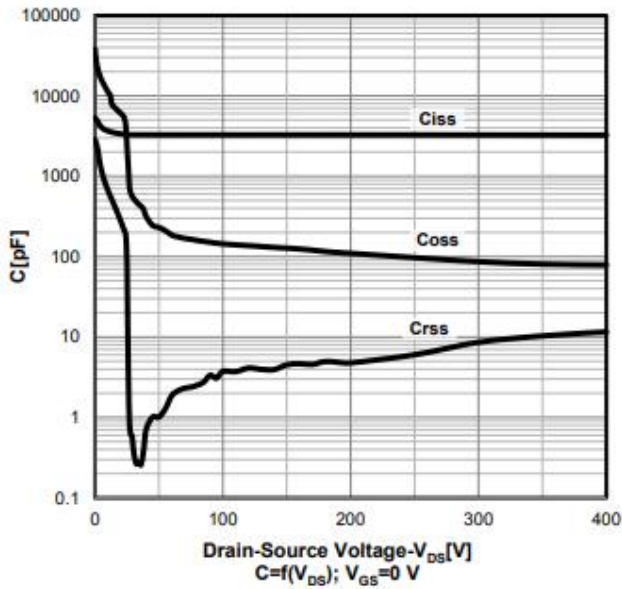
Typ. drain-source on-state resistance



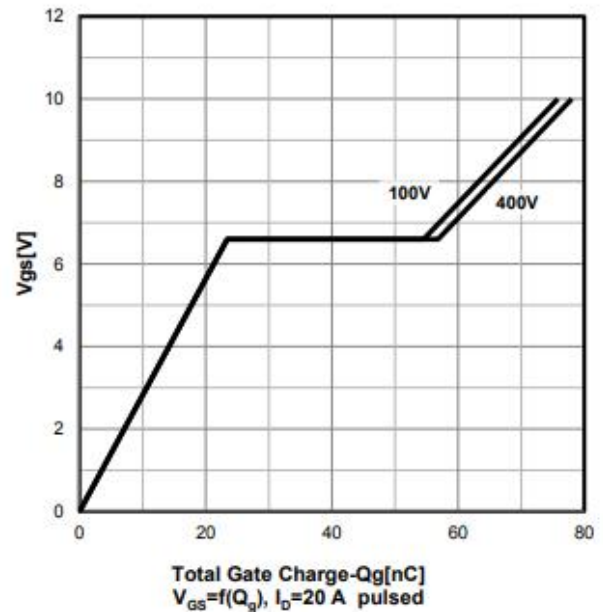
Typ. On-resistance vs temperature



Typ. capacitances

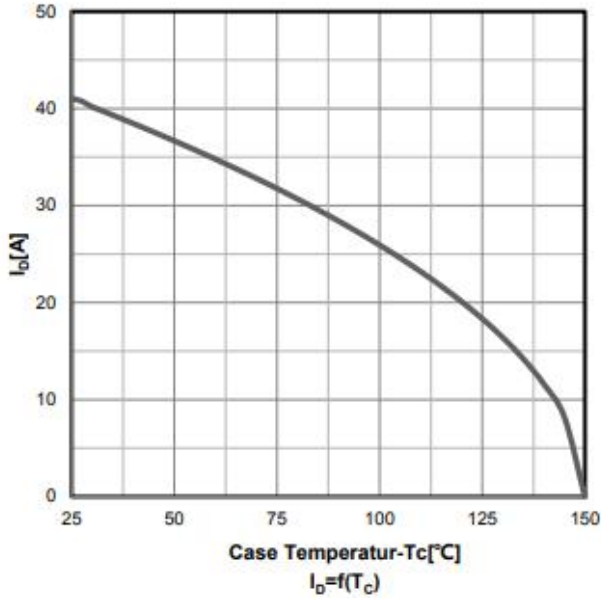


Typ. gate charge characteristics

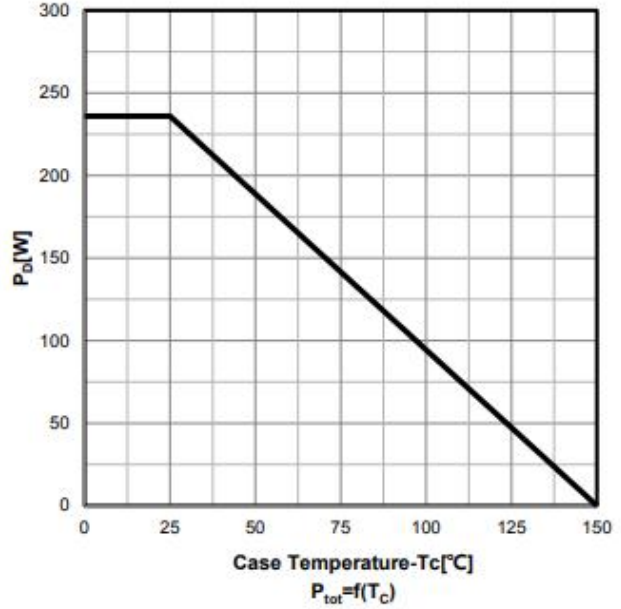


## Typical Performance Characteristics

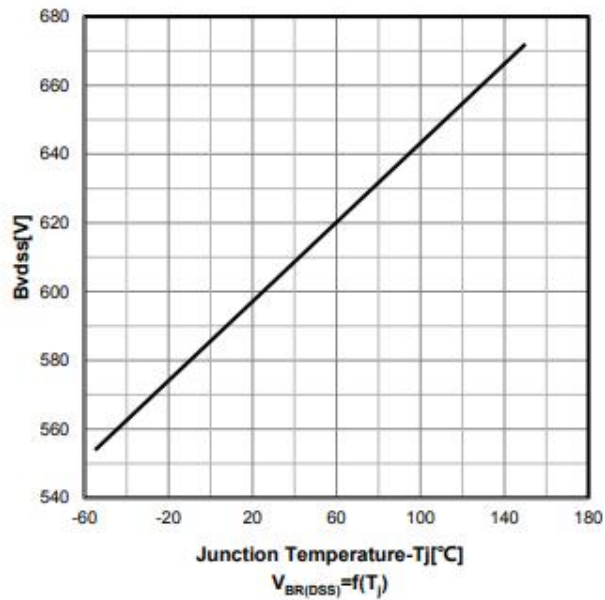
Typ. Drain current vs temperature



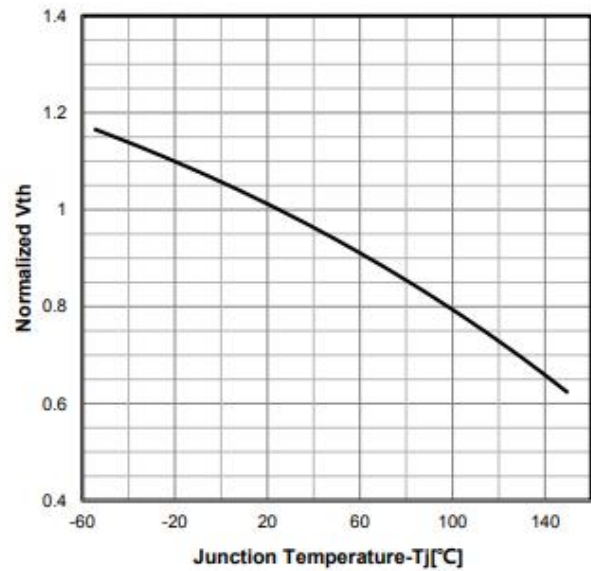
Typ. Power dissipation



Typ. Drain-source breakdown voltage

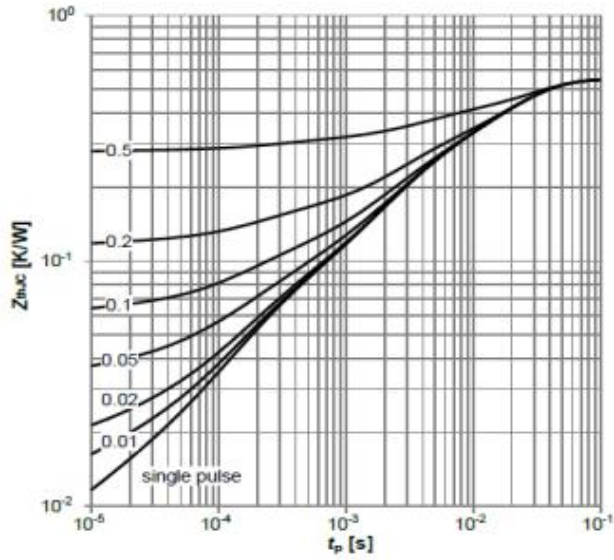


Typ. Normalized VGS(th) characteristics

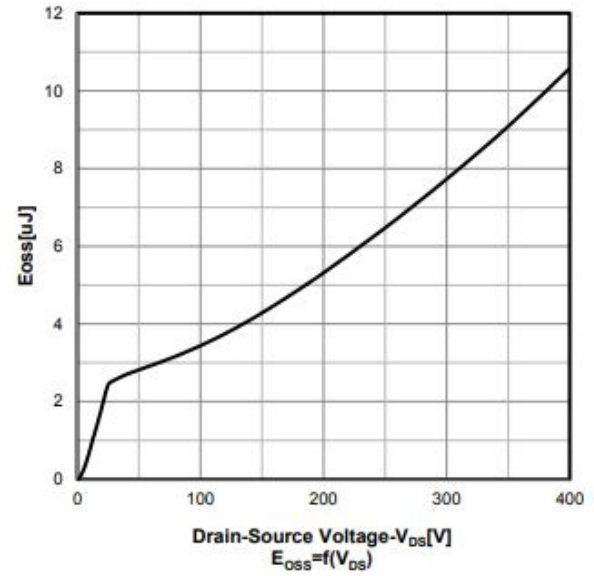


## Typical Performance Characteristics

Max. transient thermal impedance



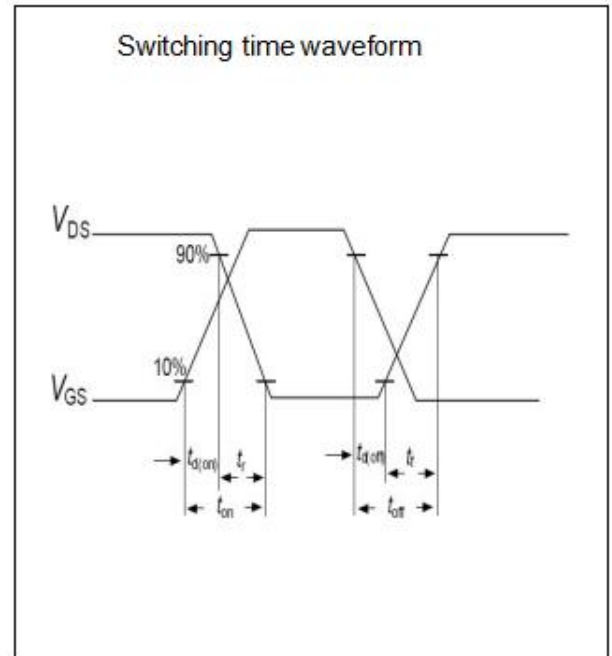
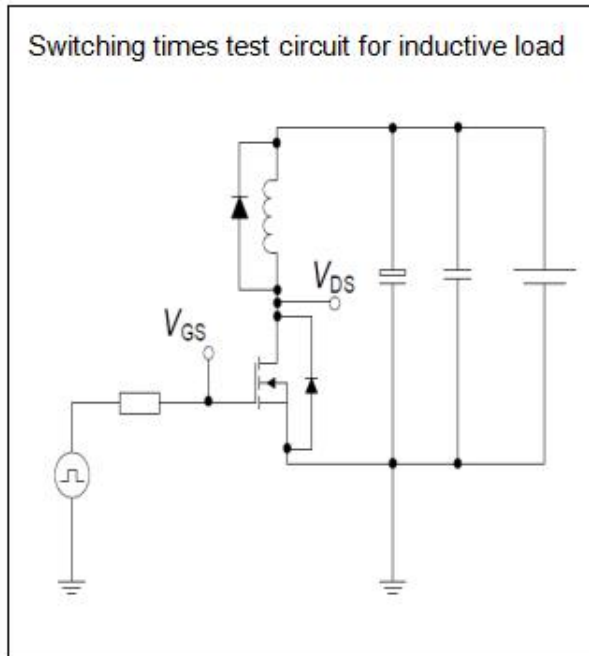
Typ. Coss stored energy



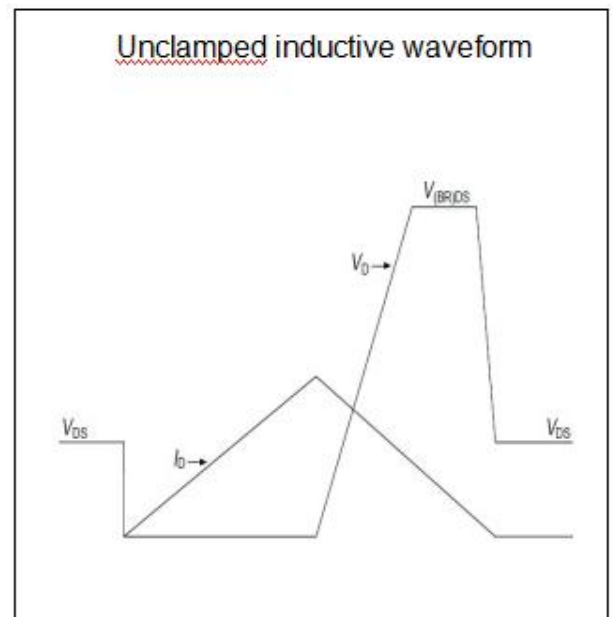
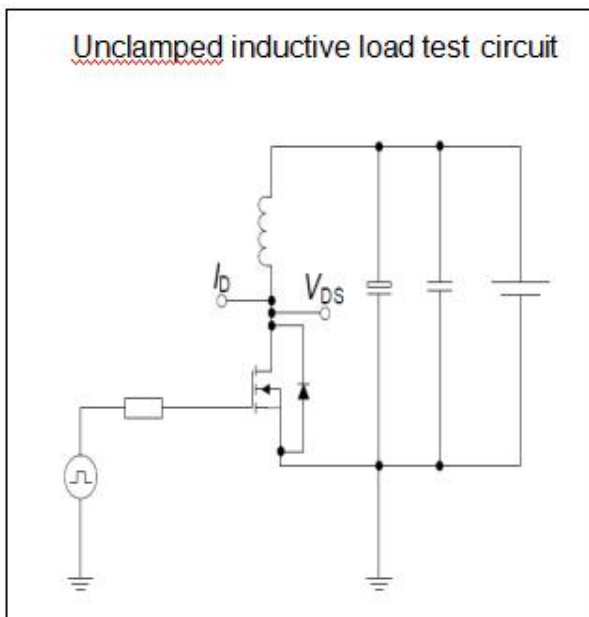


## Test circuits

### Switching times test circuit and waveform for inductive load

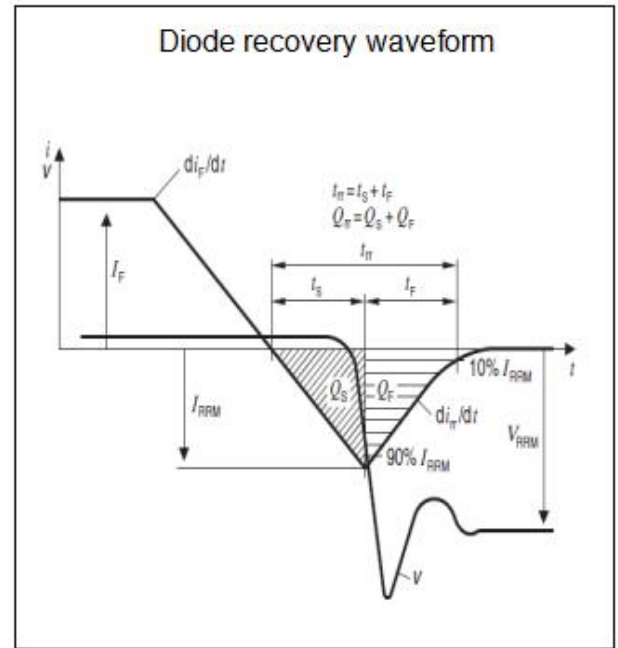
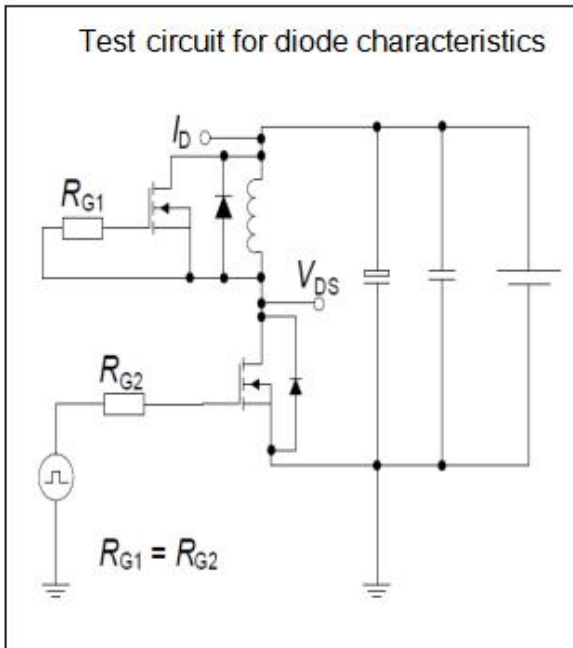


### Unclamped inductive load test circuit and waveform



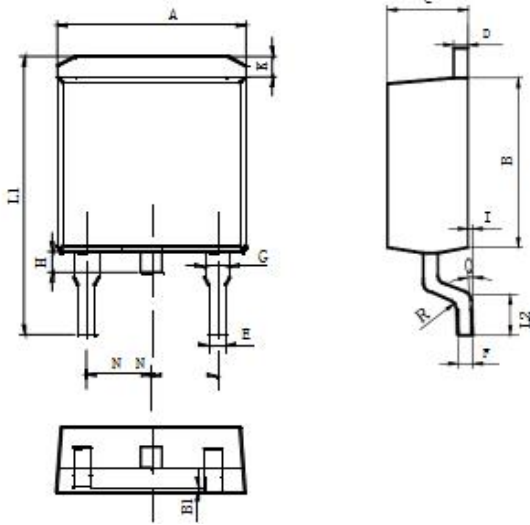
## Test circuits

### Test circuit and waveform for diode characteristics



## Package Outline

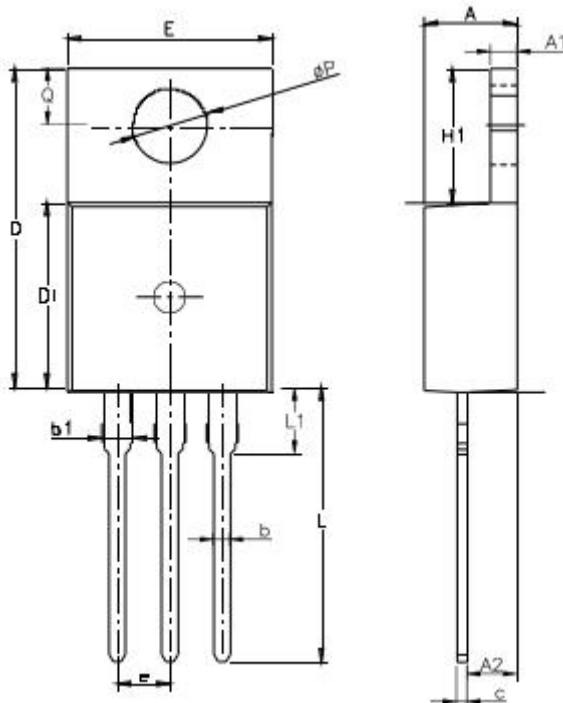
### TO-263-2L



Items	Values(mm)		
	MIN	NOM	MAX
A	9.8	10	10.4
B	8.9	9.6	9.5
B1	0	-	0.1
C	4.4	4.5	4.8
D	1.16	1.4	1.5
E	0.7	0.75	0.95
F	0.3	0.45	0.6
G	1.07	1.38	1.47
H	1.3	-	1.8
K	0.95	1	1.37
L1	14.5	15.2	16.5
L2	1.6	2	2.3
I	0	-	0.2
Q	0°	3°	8°
R	0.4		
N	2.35	2.4	2.7

## Package Outline

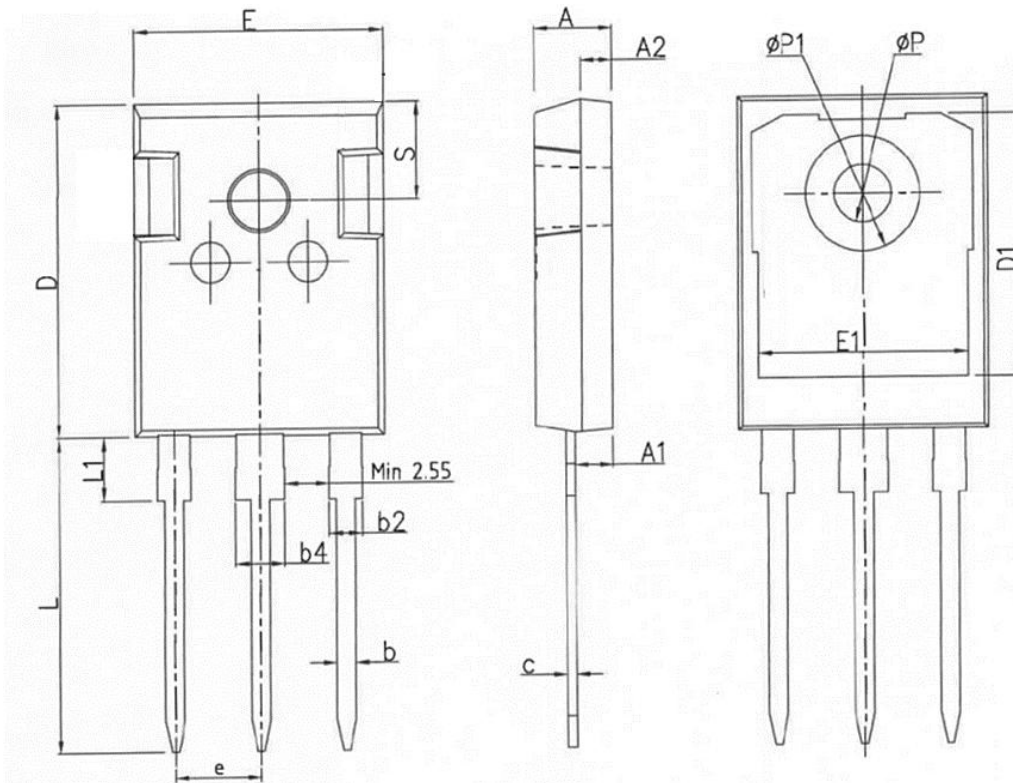
### TO-220-3L



Items	Values(mm)		
	MIN	NOM	MAX
A	4.3	4.5	4.7
A1	1	1.3	1.5
A2	1.8	2.4	2.8
b	0.6	0.8	1
b1	1	-	1.6
c	0.3	-	0.7
D	15.1	15.7	16.1
D1	8.1	9.2	10
F	9.6	9.9	10.4
e	2.54BSC		
H1	6.1	6.5	7
L	12.6	13.08	13.6
L1			3.95
ΦP	3.4	3.7	3.9
Q	2.6		3.2

## Package Outline

TO-247-3L



Items	Values(mm)		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.20	2.40	2.60
A2	1.85	2.00	2.15
b	1.10	1.20	1.35
b2	1.91	2.04	2.21
b4	2.91	3.04	3.21
c	0.50	0.60	0.75
D	20.70	21.00	21.30
D1	16.20	16.55	16.90
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
e	5.44BSC		
L	19.60	19.95	20.30
L1	-	-	4.30
$\Phi P$	3.40	3.60	3.80
$\Phi P1$	-	-	7.50
S	6.15BSC		